

PRODUCT:

CHIP ON BOARD LED

FEATURES:

27 mm x 27 mm x 0.5 mm chip-on-board LED
 120° emission angle
 95 min Ra



DESCRIPTION

YUJILEDS® BC270H series high CRI COB provides high CRI, high luminous flux solution. Providing 95 CRI (typical) at 28000 lm, this high-power LED can be used in a variety of applications demanding high color quality and light output.



ELECTRICAL-OPTICAL CHARACTERISTICS (T _A = 25 °C)							
PARAMETER	SYMBOL	VALUE			UNIT	TOLERANCE	CONDITION
		MIN.	TYP.	MAX.			
Forward voltage	V _f	35	--	42	V	±0.05	I _f = 12A
Thermal resistance*	R _{th}	--	0.10	--	°C/W	±0.01	I _f = 12A
Luminous flux	Φ _{3200K}	18000	--	24000	lm	--	I _f = 12A
	Φ _{5600K}	22000		28000			
Correlated color temperature	CCT _{3200K}	3050	3200	3350	K	--	I _f = 12A
	CCT _{5600K}	5300	5600	5900			
Color rendering index	R _a	95	--	--	--	±1	I _f = 12A
TCS R9 (CRI Red)	R ₉	--	90	--	--	--	I _f = 12A
Chromaticity coordinates	(X,Y)	--	--	--	--	±0.005	--
Reverse current	I _r	--	--	100	μA	±0.1	V _r = 50V
Viewing angle	2θ _{1/2}	--	120	--	Deg	±5	I _f = 12A

*The definition of Thermal Resistance is between LED junction and COB bottom surface.
 Junction Temperature T_j = T_b + Power(W) x R_{th}, where T_b is the temperature at COB bottom surface.

ABSOLUTE MAXIMUM RATING (T _A = 25 °C)			
PARAMETER	SYMBOL	LIMIT	UNIT
Power Consumption	P _D	500	W
DC Forward Current (pulsed)*	I _{Fp}	15000**	mA
DC Forward Current	I _F	12000	mA
Reverse Voltage	V _R	50	V
Junction Temperature	T _j	150	°C
Case Temperature***	T _c	60	°C
Operating Temperature	T _{opr}	-30 ~ +60	°C
Storage Temperature	T _{stg}	-30 ~ +80	°C
Soldering Temperature	T _{sol}	260 ± 5	°C
Reflow Cycles Allowed	--	2	--

* Pulse width ≤ 0.1ms, Duty ≤ 1/10.

** Theoretical data.

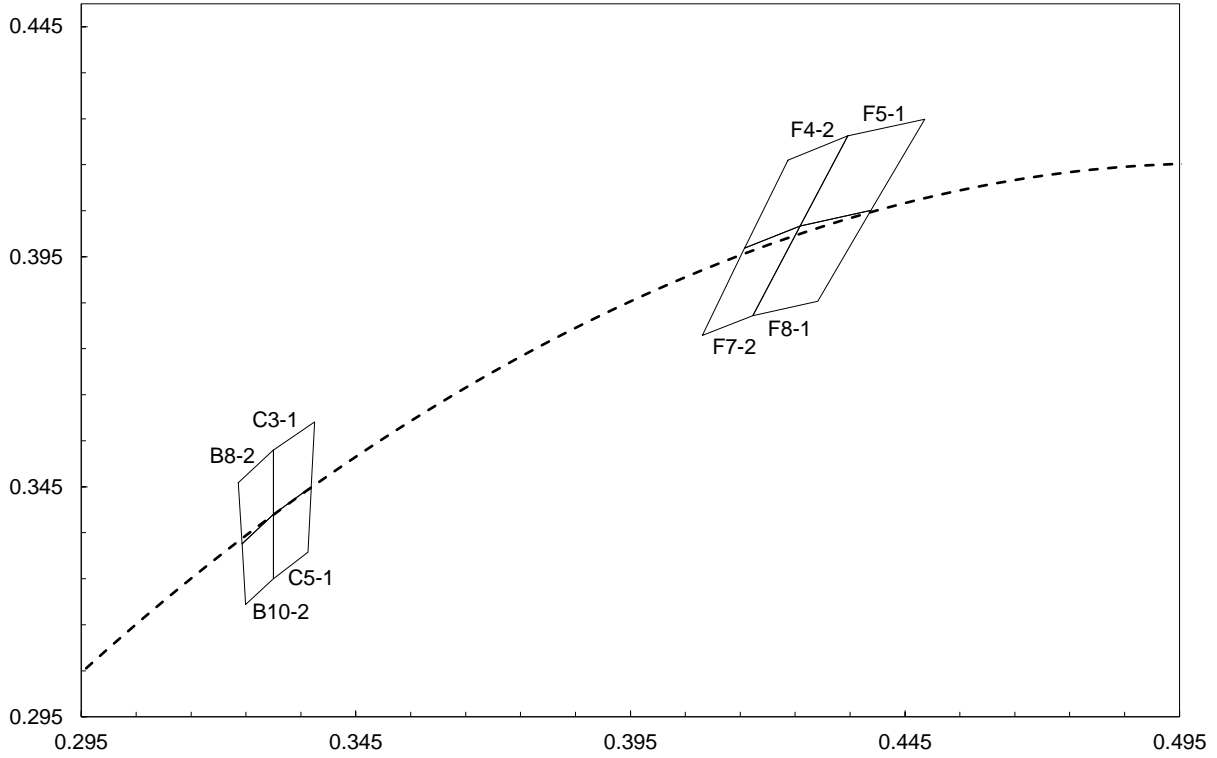
*** See page 5 for case temperature point definition.

ORDERING INFORMATION		
PART NUMBER	CCT	CHROMATICITY BINS
YJ-BC-270H-G02-32	3200K ± 150K	F4-2, F7-2, F5-1, F8-1
YJ-BC-270H-G02-56	5600K ± 300K	B8-2, B10-2, C3-1, C5-1
YJ-BC-270H-G02-XX	CUSTOM	--

CHROMATICITY BINS & COORDINATES									
CCT	BIN	CIE 1931 COORDINATES							
		X0	Y0	X1	Y1	X2	Y2	X3	Y3
5600K	B8-2	0.3236	0.3459	0.3243	0.3326	0.3300	0.3390	0.3300	0.3530
	B10-2	0.3243	0.3326	0.3249	0.3194	0.3300	0.3250	0.3300	0.3390
	C3-1	0.3300	0.3530	0.3300	0.3390	0.3369	0.3450	0.3375	0.3591
	C5-1	0.3300	0.3390	0.3300	0.3250	0.3363	0.3308	0.3369	0.3450
3200K	F4-2	0.4237	0.4160	0.4158	0.3969	0.4259	0.4017	0.4346	0.4213
	F7-2	0.4158	0.3969	0.4081	0.3779	0.4173	0.3822	0.4259	0.4017
	F5-1	0.4346	0.4213	0.4259	0.4017	0.4388	0.4051	0.4486	0.4249
	F8-1	0.4259	0.4017	0.4173	0.3822	0.4291	0.3853	0.4388	0.4051

CHROMATICITY BINS & COORDINATES

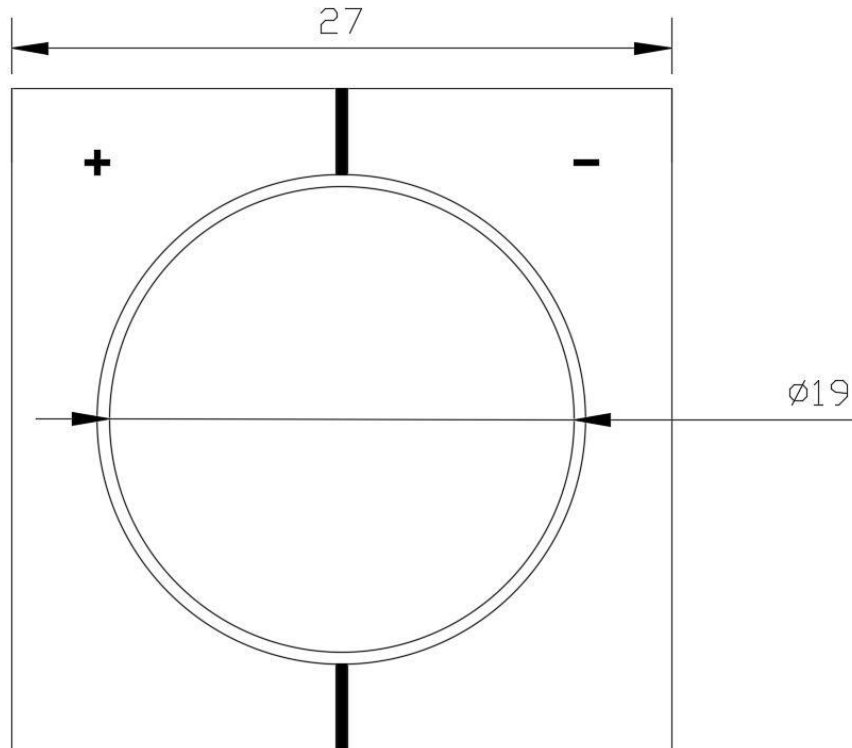
CIE 1931 COORDINATES



MECHANICAL DIMENSION

COB – Top View

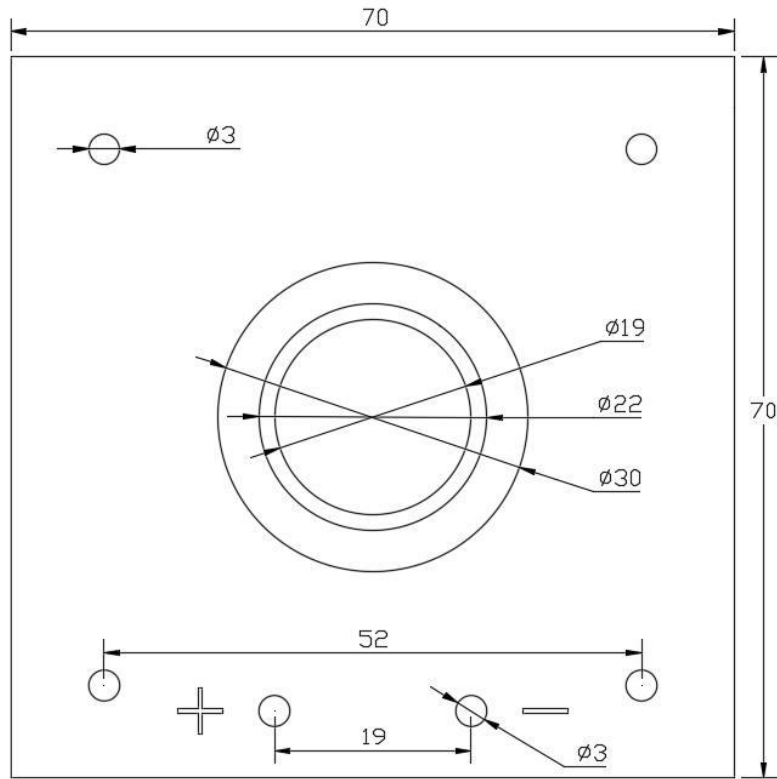
All dimensions in mm, tolerance unless mentioned is $\pm 0.1\text{mm}$.



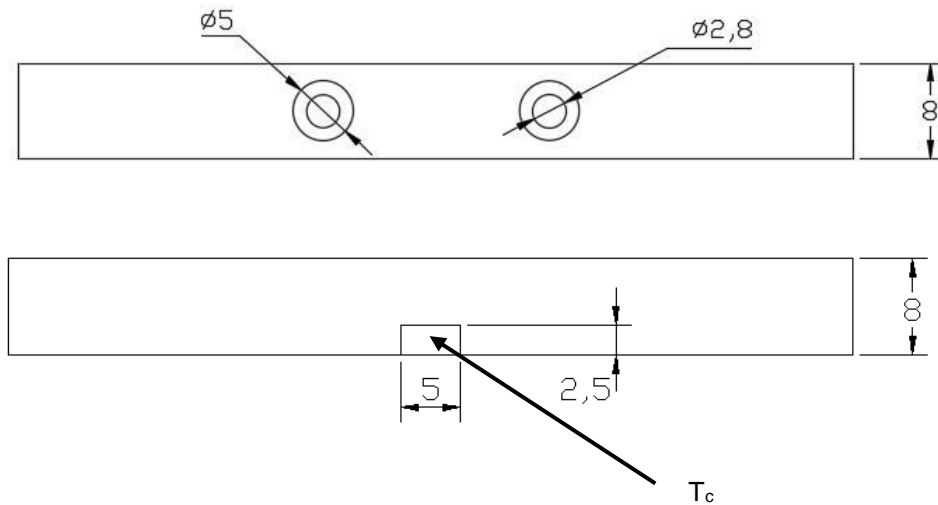
COB – Lateral View



Baseplate – Top View



Baseplate – Lateral View

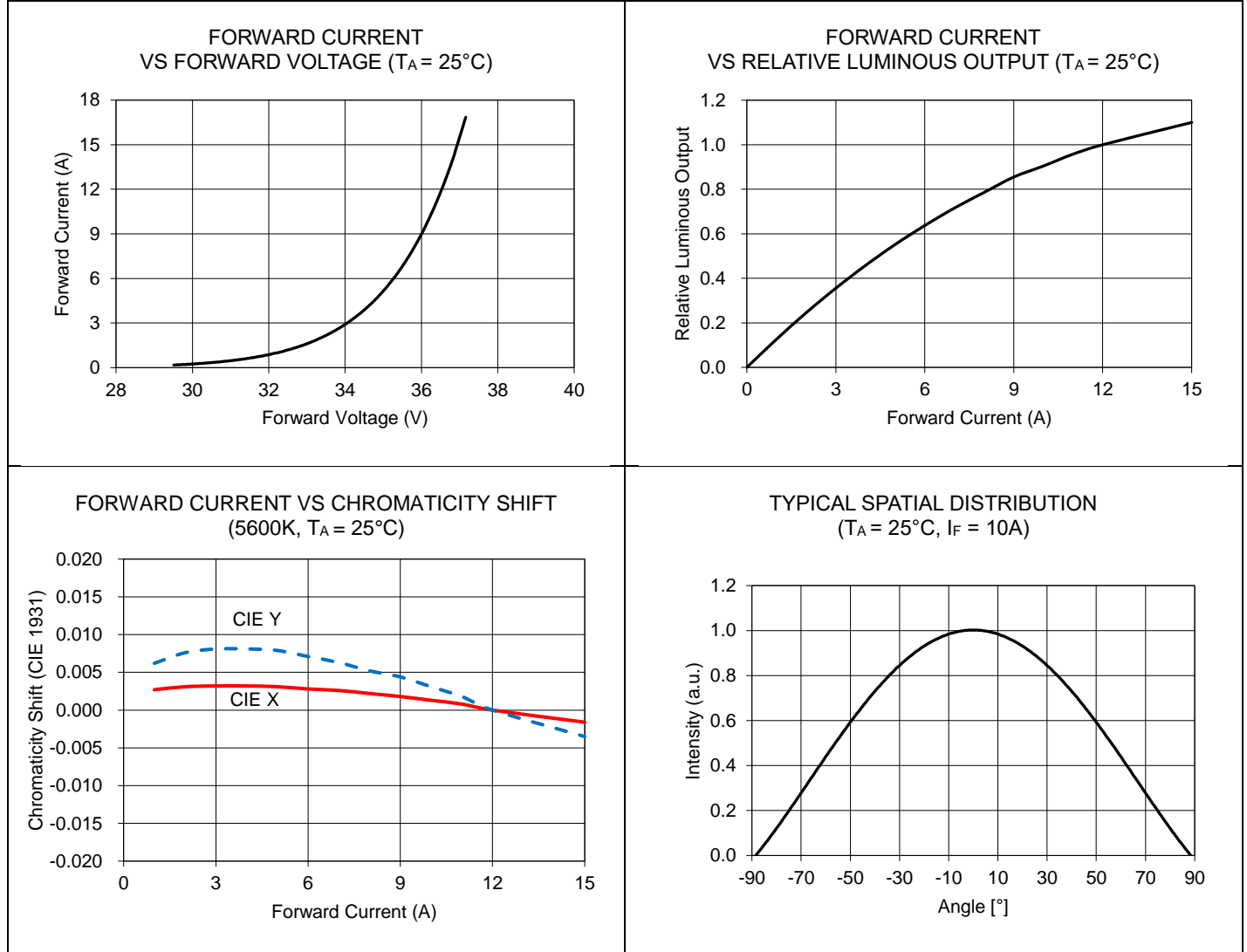


The material of black cover plate is composite stone.
All measurements are $\pm 0.5\text{mm}$ unless otherwise indicated.

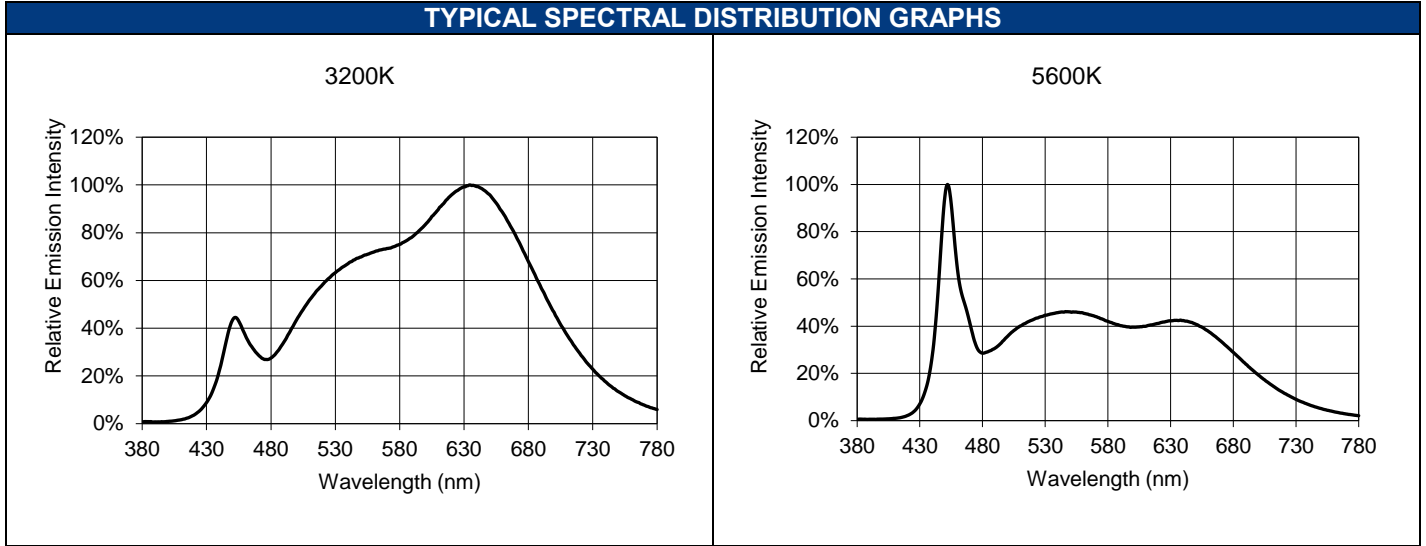
MATERIALS	
ITEM	DESCRIPTION
DIE MATERIAL	InGaN
SUBSTRATE	AlN
ENCAPSULANT RESIN MATERIAL	SILICONE + PHOSPHOR

CHARACTERISTIC CURVES

ALL CHARACTERISTIC CURVES ARE FOR REFERENCE ONLY AND NOT GUARANTEED



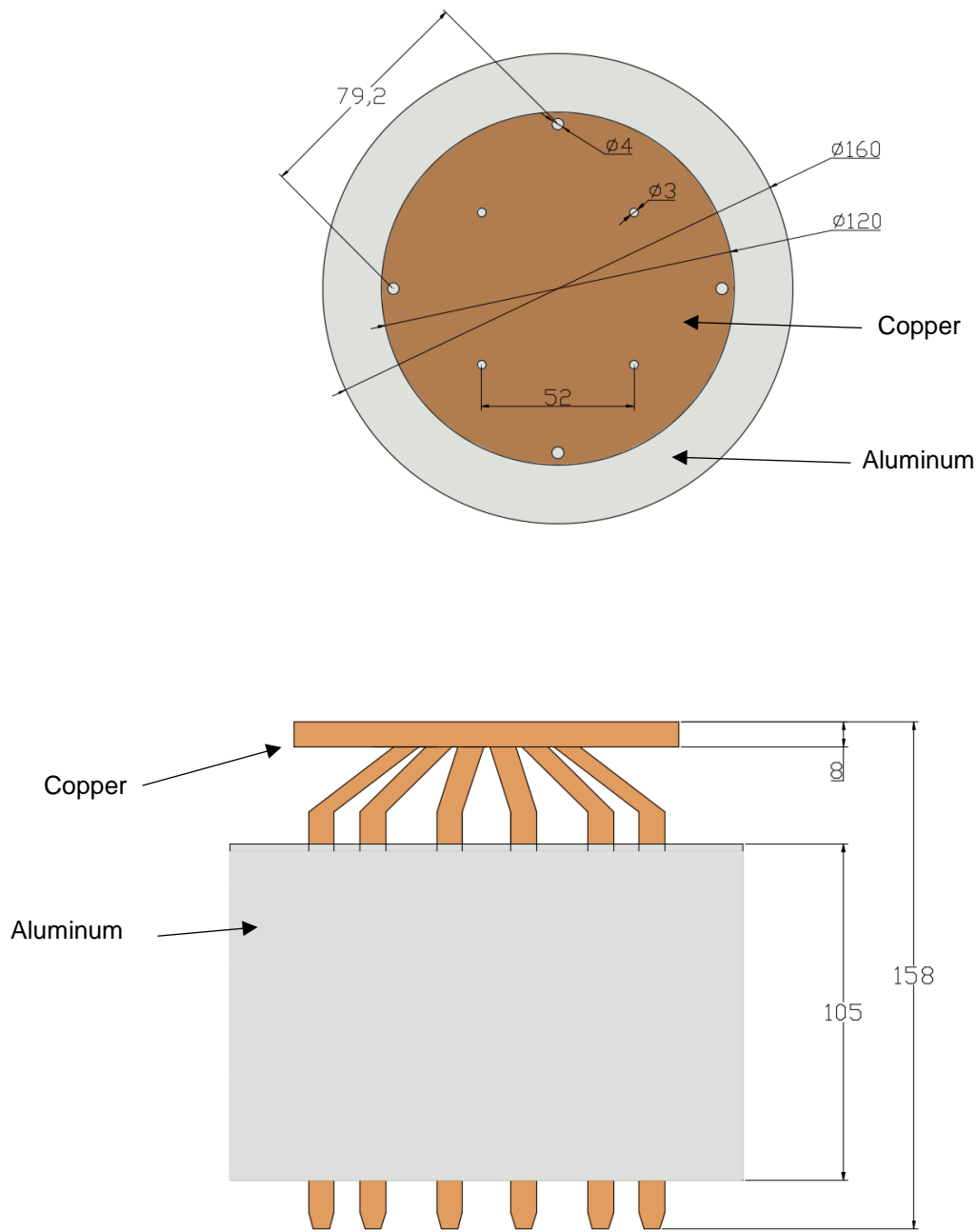
TYPICAL SPECTRAL DISTRIBUTION GRAPHS



Optional Accessory - Radiator

MECHANICAL DIMENSION

All dimensions in mm, tolerance unless mentioned is $\pm 0.1\text{mm}$.



Weight = 2.1Kg

All measurements are $\pm 0.5\text{mm}$ unless otherwise indicated.
The dimension of radiator is only for reference.

PICTURE OF RADIATOR

